Product Change Notice

(PCN Tracking Number: EE-QR-221130-01)

Version: 1

Customer:	ALL Customers
Renesas Product Type:	R8A774C0HA01BG#UA, R8A774C0HA01BG#GA
Description of Change:	Addition of Assembly site and package substrate change due to adding Assembly (OS) site.
Reason for Change:	For stable supply and productivity improvement
Identification:	Production history data can be queried by using the trace code of the product.
Schedules:	Reliability report: e/o May 2023 (upon request) Sample order: e/o Dec. 2022 (upon request) Requested approval: b/o Mar. 2023 Change Implementation: b/o Oct. 2023 onwards
Anticipated Impact:	Form & Functionality: No impact Fit: Slight change in package height and substrate thickness (see p.2) Quality & Reliability: No impact
Doc. No.:	EE-QC-PCN-CR-22-0224
Internal Reference:	EPMP-IMB-22-0250-1

In case of any question, please contact:

INITIATOR	TITLE	E-mail	PHONE No.
Farhad Banihashemi	Staff Engineer	farhad.banihashemi@renesas.com	+49-211-6503-1844

Düsseldorf, 02.12.2022

Customer Response:

(please fill in and return by e-mail, fax or mail)

☐ acknowledge
☐ acceptable
☐ inacceptable (pls. comment)
☐ not applicable

Company: ______________________________

Name & Position: ______________________________

Phone / Fax No.: ______________________________

Note: Acknowledgement must be received by Renesas within 30 days or Renesas will consider the change as approved. If timely acknowledgement is provided by Customer, then Customer shall have 90 days from the date of receipt of this PCN in which to make any objections to the PCN. If Customer fails to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved. If customer cannot accept the PCN, they must provide Renesas with a last time buy demand and purchase order.

Comments:

______________________________ (Signature)

Details of Change:

Differences between current MP product and product in additional assembly site.

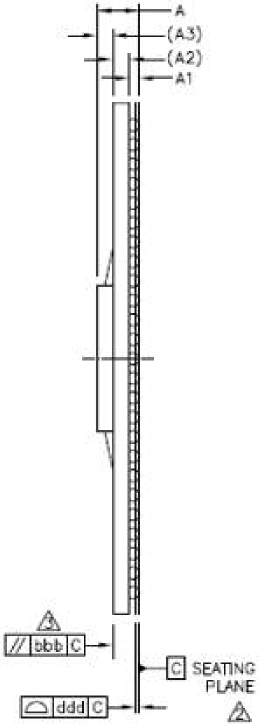
(1) PKG height and substrate thickness

（A） PKG Height: A in the figure

＜Additional OS＞	＜Current MP OS＞
1.84mmMax	2.45mmMax

（B） PKG substrate thickness: A2 in the figure

＜Additional OS＞	＜Current MP OS＞
0.688mmMax	1.176mmMax



(2) There are differences in mold color and laser mark font/color due to OS site standard process.

(3) Along with the external shape change, there are tray changes and packing specification changes. We will update the delivery specifications before the reliability test completion.